



2M (128K x 16) Static RAM

Features

- Very high speed: 55 ns and 70 ns
- Temperature Ranges
 - Industrial: -40°C to +85°C
 - Automotive: -40°C to +125°C
- Pin-compatible with the CY62137V
- Ultra-low active power
 - Typical active current: 1.5 mA @ f = 1 MHz
 - Typical active current: 5.5 mA @ f = f_{max} (70-ns speed)
- Low and ultra-low standby power
- Easy memory expansion with \overline{CE} and \overline{OE} features
- Automatic power-down when deselected
- CMOS for optimum speed/power
- Packages offered in a Lead-Free and Non-Lead Free 48-ball FBGA

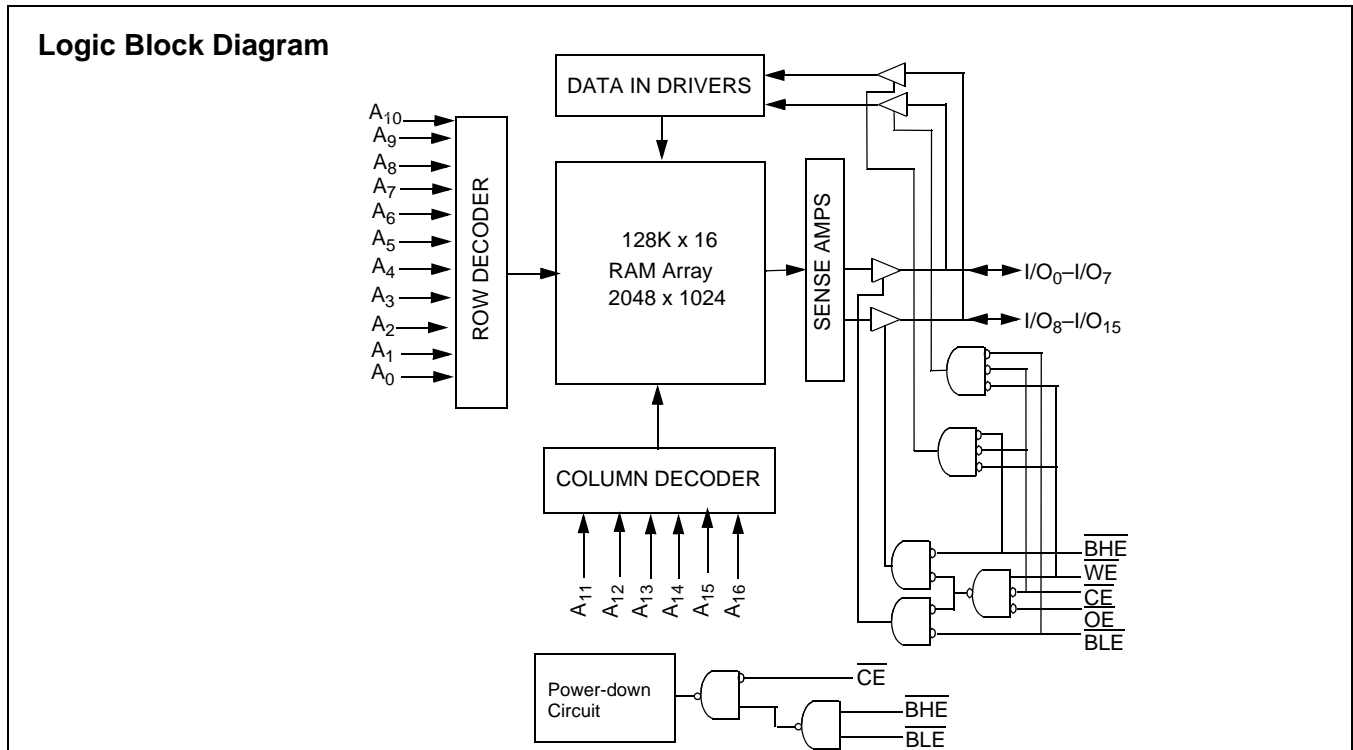
Functional Description^[1]

The CY62137CV25/30/33 and CY62137CV are high-performance CMOS static RAMs organized as 128K words by 16 bits. These devices feature advanced circuit design to provide ultra-low active current. This is ideal for providing More Battery

Life™ (MoBL[®]) in portable applications such as cellular telephones. The devices also has an automatic power-down feature that significantly reduces power consumption by 80% when addresses are not toggling. The device can also be put into standby mode reducing power consumption by more than 99% when deselected (\overline{CE} HIGH or both \overline{BLE} and \overline{BHE} are HIGH). The input/output pins (I/O₀ through I/O₁₅) are placed in a high-impedance state when: deselected (\overline{CE} HIGH), outputs are disabled (\overline{OE} HIGH), both \overline{Byte} High Enable and \overline{Byte} Low Enable are disabled (\overline{BHE} , \overline{BLE} HIGH), or during a write operation (\overline{CE} LOW, and \overline{WE} LOW).

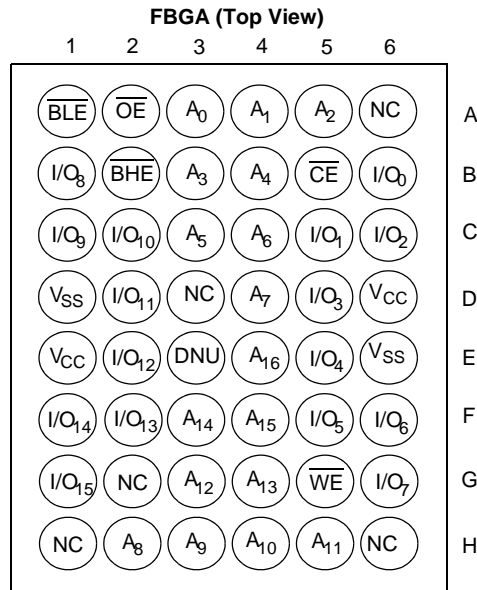
Writing to the device is accomplished by taking Chip Enable (\overline{CE}) and Write Enable (\overline{WE}) inputs LOW. If \overline{Byte} Low Enable (\overline{BLE}) is LOW, then data from I/O pins (I/O₀ through I/O₇), is written into the location specified on the address pins (A₀ through A₁₆). If \overline{Byte} High Enable (\overline{BHE}) is LOW, then data from I/O pins (I/O₈ through I/O₁₅) is written into the location specified on the address pins (A₀ through A₁₆).

Reading from the device is accomplished by taking Chip Enable (\overline{CE}) and Output Enable (\overline{OE}) LOW while forcing the Write Enable (\overline{WE}) HIGH. If \overline{Byte} Low Enable (\overline{BLE}) is LOW, then data from the memory location specified by the address pins will appear on I/O₀ to I/O₇. If \overline{Byte} High Enable (\overline{BHE}) is LOW, then data from memory will appear on I/O₈ to I/O₁₅. See the truth table at the back of this data sheet for a complete description of read and write modes.



Note:

1. For best practice recommendations, please refer to the Cypress application note "System Design Guidelines" on <http://www.cypress.com>.

Pin Configuration^[2, 3]

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature -65°C to +150°C
 Ambient Temperature with Power Applied..... -55°C to +125°C
 Supply Voltage to Ground Potential -0.5V to V_{CCMAX} + 0.5V
 DC Voltage Applied to Outputs in High-Z State^[4] -0.5V to V_{CC} + 0.3V
 DC Input Voltage^[4] -0.5V to V_{CC} + 0.3V
 Output Current into Outputs (LOW) 20 mA

Static Discharge Voltage..... > 2001V
 (per MIL-STD-883, Method 3015)

Latch-up Current > 200 mA

Operating Range

Device	Range	Ambient Temperature T _A	V _{CC}
CY62137CV25	Industrial	-40°C to +85°C	2.2V to 2.7V
CY62137CV30			2.7V to 3.3V
CY62137CV33			3.0V to 3.6V
CY62137CV			2.7V to 3.6V
CY62137CV30	Automotive	-40°C to +125°C	2.7V to 3.3V

Product Portfolio

Product	Range	V _{CC} Range (V)		Speed (ns)	Power Dissipation						
					Operating, I _{CC} (mA)				Standby, I _{SB2} (μA)		
					f = 1 MHz		f = f _{max}				
Min.	Typ. ^[5]	Max.	Typ. ^[5]	Max.	Typ. ^[5]	Max.	Typ. ^[5]	Max.			
CY62137CV25LL	Industrial	2.2	2.5	2.7	55	1.5	3	7	15	2	10
					70	1.5	3	5.5	12		
CY62137CV30LL	Industrial	2.7	3.0	3.3	55	1.5	3	7	15	2	10
					70	1.5	3	5.5	12		
CY62137CV30LL	Automotive	2.7	3.0	3.3	70	1.5	3	5.5	15	2	15
CY62137CV33LL	Industrial	3.0	3.3	3.6	55	1.5	3	7	15	5	15
					70	1.5	3	5.5	12		
CY62137CVLL	Industrial	2.7V	3.3	3.6	70	1.5	3	5.5	12	5	15
CY62137CVSL	Industrial	2.7V	3.3	3.6	70	1.5	3	5.5	12	1	5

Notes:

2. NC pins are not connected to the die.
3. E3 (DNU) can be left as NC or V_{SS} to ensure proper application.
4. V_{IL(min.)} = -2.0V for pulse durations less than 20 ns.
5. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = V_{CC(typ.)}, T_A = 25°C.



Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions		CY62137CV25-55			CY62137CV25-70			Unit
				Min.	Typ. ^[5]	Max.	Min.	Typ. ^[5]	Max.	
V _{OH}	Output HIGH Voltage	I _{OH} = -0.1 mA	V _{CC} = 2.2V	2.0			2.0			V
V _{OL}	Output LOW Voltage	I _{OL} = 0.1 mA	V _{CC} = 2.2V			0.4			0.4	V
V _{IH}	Input HIGH Voltage			1.8		V _{CC} + 0.3V	1.8		V _{CC} + 0.3V	V
V _{IL}	Input LOW Voltage			-0.3		0.6	-0.3		0.6	V
I _{IX}	Input Leakage Current	GND ≤ V _I ≤ V _{CC}		-1		+1	-1		+1	μA
I _{OZ}	Output Leakage Current	GND ≤ V _O ≤ V _{CC} , Output Disabled		-1		+1	-1		+1	μA
I _{CC}	V _{CC} Operating Supply Current	f = f _{MAX} = 1/t _{RC}	V _{CC} = 2.7V		7	15		5.5	12	mA
		f = 1 MHz	I _{OUT} = 0 mA CMOS Levels		1.5	3		1.5	3	
I _{SB1}	Automatic CE Power-down Current—CMOS Inputs	CE ≥ V _{CC} - 0.2V V _{IN} ≥ V _{CC} - 0.2V or V _{IN} ≤ 0.2V, f = f _{max} (Address and Data Only), f=0 (OE, WE, BHE, and BLE)			2	10		2	10	μA
I _{SB2}	Automatic CE Power-down Current—CMOS Inputs	CE ≥ V _{CC} - 0.2V V _{IN} ≥ V _{CC} - 0.2V or V _{IN} ≤ 0.2V, f = 0, V _{CC} = 2.7V								

Parameter	Description	Test Conditions		CY62137CV30-55			CY62137CV30-70			Unit	
				Min.	Typ. ^[5]	Max.	Min.	Typ. ^[5]	Max.		
V _{OH}	Output HIGH Voltage	I _{OH} = -1.0 mA	V _{CC} = 2.7V	2.4			2.4			V	
V _{OL}	Output LOW Voltage	I _{OL} = 2.1 mA	V _{CC} = 2.7V			0.4			0.4	V	
V _{IH}	Input HIGH Voltage			2.2		V _{CC} + 0.3V	2.2		V _{CC} + 0.3V	V	
V _{IL}	Input LOW Voltage			-0.3		0.8	-0.3		0.8	V	
I _{IX}	Input Leakage Current	GND ≤ V _I ≤ V _{CC}		Ind'l	-1	+1	-1	+1	μA		
				Auto			-2	+2			
I _{OZ}	Output Leakage Current	GND ≤ V _O ≤ V _{CC} , Output Disabled		Ind'l	-1	+1	-1	+1	μA		
				Auto			-2	+2			
I _{CC}	V _{CC} Operating Supply Current	f = f _{MAX} = 1/t _{RC}	V _{CC} = 3.3V	Ind'l		7	15		5.5	12	mA
		f = 1 MHz	I _{OUT} = 0 mA CMOS Levels	Auto					5.5	15	
I _{SB1}	Automatic CE Power-down Current—CMOS Inputs	CE ≥ V _{CC} - 0.2V V _{IN} ≥ V _{CC} - 0.2V or V _{IN} ≤ 0.2V, f = f _{max} (Address and Data Only), f=0 (OE, WE, BHE, and BLE)		Ind'l		2	10		2	10	μA
				Auto					2	15	
I _{SB2}	Automatic CE Power-down Current—CMOS Inputs	CE ≥ V _{CC} - 0.2V V _{IN} ≥ V _{CC} - 0.2V or V _{IN} ≤ 0.2V f = 0, V _{CC} = 3.3V		Ind'l		2	10		2	10	μA
				Auto					2	15	

Electrical Characteristics Over the Operating Range

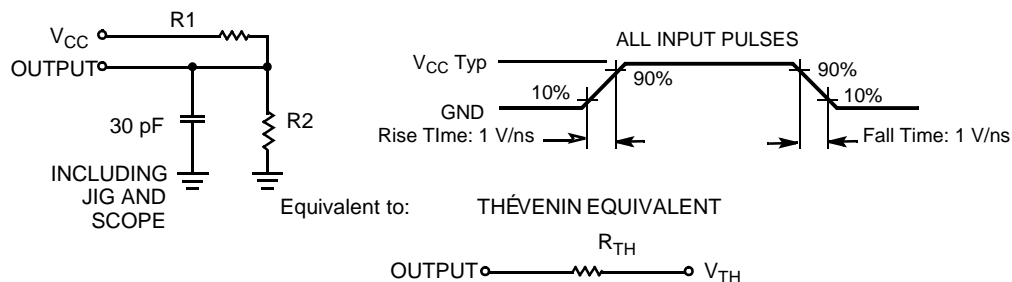
Parameter	Description	Test Conditions	CY62137CV33-55			CY62137CV33-70 CY62137CV-70			Unit	
			Min.	Typ. ^[5]	Max.	Min.	Typ. ^[5]	Max.		
V _{OH}	Output HIGH Voltage	I _{OH} = -1.0 mA	V _{CC} = 3.0V	2.4			2.4			V
			V _{CC} = 2.7V				2.4			V
V _{OL}	Output LOW Voltage	I _{OL} = 2.1 mA	V _{CC} = 3.0V			0.4			0.4	V
			V _{CC} = 2.7V						0.4	V
V _{IH}	Input HIGH Voltage		2.2		V _{CC} + 0.3V	2.2		V _{CC} + 0.3V	V	
V _{IL}	Input LOW Voltage		-0.3		0.8	-0.3		0.8	V	
I _{IX}	Input Leakage Current	GND ≤ V _I ≤ V _{CC}	-1		+1	-1		+1	μA	
I _{OZ}	Output Leakage Current	GND ≤ V _O ≤ V _{CC} , Output Disabled	-1		+1	-1		+1	μA	
I _{CC}	V _{CC} Operating Supply Current	f = f _{MAX} = 1/t _{RC}	V _{CC} = 3.6V I _{OUT} = 0 mA CMOS Levels	7	15	5.5	12	mA		
		f = 1 MHz		1.5	3				1.5	3
I _{SB1}	Automatic CE Power-down Current —CMOS Inputs	CE ≥ V _{CC} - 0.2V V _{IN} ≥ V _{CC} - 0.2V or V _{IN} ≤ 0.2V, f = f _{max} (Address and Data Only), f=0 (OE, WE, BHE, and BLE)		5	15		5	15	μA	
I _{SB2}	Automatic CE Power-down Current —CMOS Inputs	CE ≥ V _{CC} - 0.2V V _{IN} ≥ V _{CC} - 0.2V or V _{IN} ≤ 0.2V, f = 0, V _{CC} = 3.6V	LL	5	15		5	15	μA	
			SL							1

Capacitance^[6]

Parameter	Description	Test Conditions	Max.	Unit
C _{IN}	Input Capacitance	T _A = 25°C, f = 1 MHz,	6	pF
C _{OUT}	Output Capacitance	V _{CC} = V _{CC(typ.)}	8	pF

Thermal Resistance

Parameter	Description	Test Conditions	BGA	Unit
Θ _{JA}	Thermal Resistance (Junction to Ambient) ^[6]	Still Air, soldered on a 3 x 4.5 inch, two-layer printed circuit board	55	°C/W
Θ _{JC}	Thermal Resistance (Junction to Case) ^[6]		16	°C/W

AC Test Loads and Waveforms


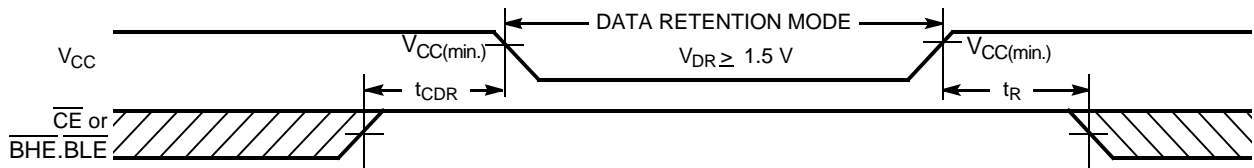
Parameters	2.5V	3.0V	3.3V	Unit
R1	16600	1105	1216	Ω
R2	15400	1550	1374	Ω
R _{TH}	8000	645	645	Ω
V _{TH}	1.20	1.75	1.75	V

Note:

6. Tested initially and after any design or process changes that may affect these parameters.

Data Retention Characteristics (Over the Operating Range)

Parameter	Description	Conditions	Min.	Typ. ^[5]	Max.	Unit
V_{DR}	V_{CC} for Data Retention		1.5		V_{CCmax}	V
I_{CCDR}	Data Retention Current	$V_{CC} = 1.5V$ $CE \geq V_{CC} - 0.2V$, $V_{IN} \geq V_{CC} - 0.2V$ or $V_{IN} \leq 0.2V$		1	6	μA
		LL	Ind'l	8		
		SL	Ind'l	4		
$t_{CDR}^{[6]}$	Chip Deselect to Data Retention Time		0			ns
$t_R^{[7]}$	Operation Recovery Time		t_{RC}			ns

Data Retention Waveform^[8]

Switching Characteristics Over the Operating Range^[9]

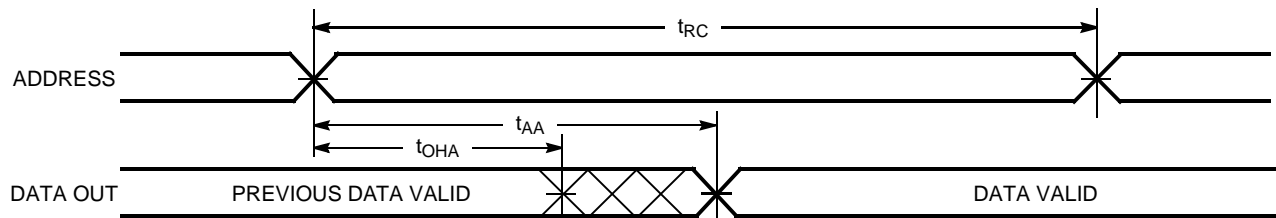
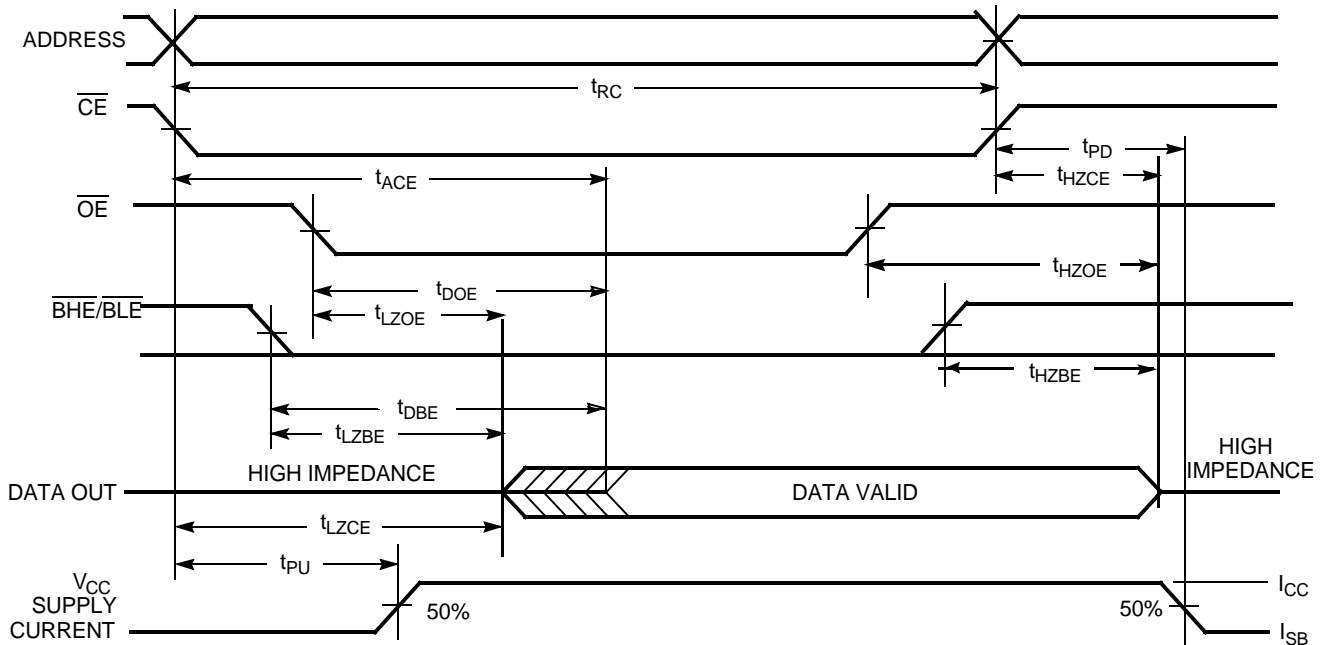
Parameter	Description	55 ns		70 ns		Unit
		Min	Max	Min	Max	
Read Cycle						
t_{RC}	Read Cycle Time	55		70		ns
t_{AA}	Address to Data Valid		55		70	ns
t_{OHA}	Data Hold from Address Change	10		10		ns
t_{ACE}	\overline{CE} LOW to Data Valid		55		70	ns
t_{DOE}	\overline{OE} LOW to Data Valid		25		35	ns
t_{LZOE}	\overline{OE} LOW to Low-Z ^[10]	5		5		ns
t_{HZOE}	\overline{OE} HIGH to High-Z ^[10, 12]		20		25	ns
t_{LZCE}	\overline{CE} LOW to Low-Z ^[10]	10		10		ns
t_{HZCE}	\overline{CE} HIGH to High-Z ^[10, 12]		20		25	ns
t_{PU}	\overline{CE} LOW to Power-up	0		0		ns
t_{PD}	\overline{CE} HIGH to Power-down		55		70	ns
t_{DBE}	$\overline{BHE}/\overline{BLE}$ LOW to Data Valid		55		70	ns
$t_{LZBE}^{[11]}$	$\overline{BHE}/\overline{BLE}$ LOW to Low-Z ^[10]	5		5		ns
t_{HZBE}	$\overline{BHE}/\overline{BLE}$ HIGH to High-Z ^[10, 12]		20		25	ns
Write Cycle^[13]						
t_{WC}	Write Cycle Time	55		70		ns
t_{SCE}	\overline{CE} LOW to Write End	45		60		ns
t_{AW}	Address Set-up to Write End	45		60		ns

Notes:

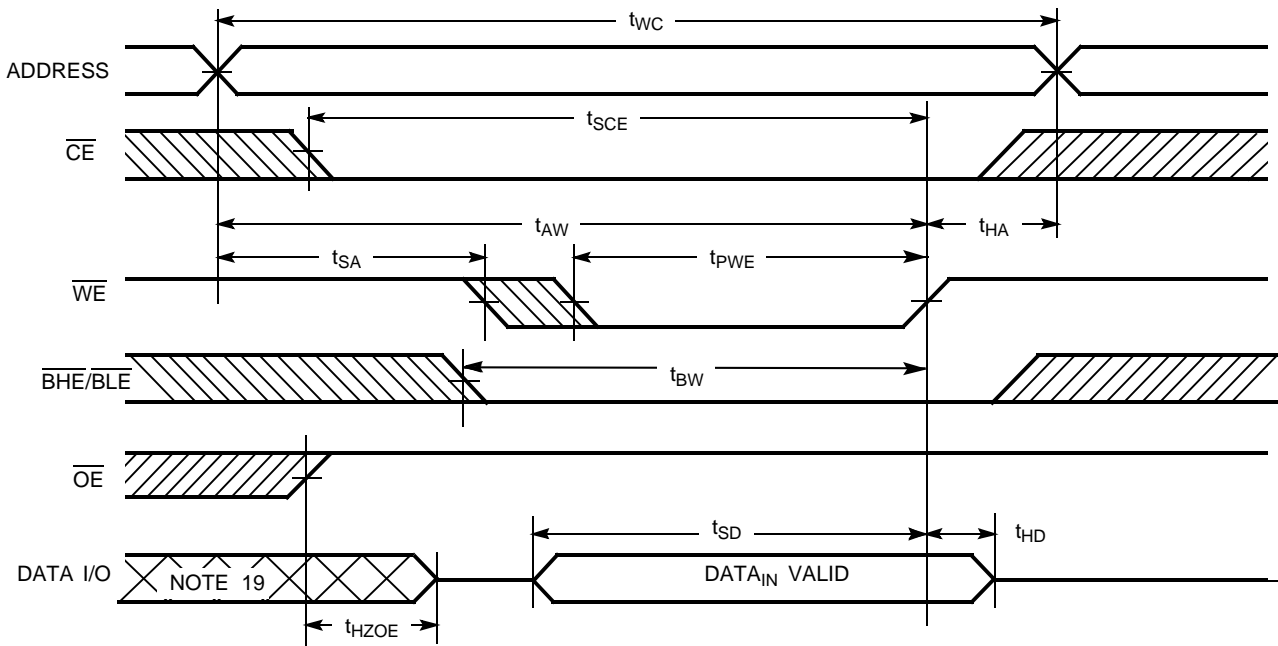
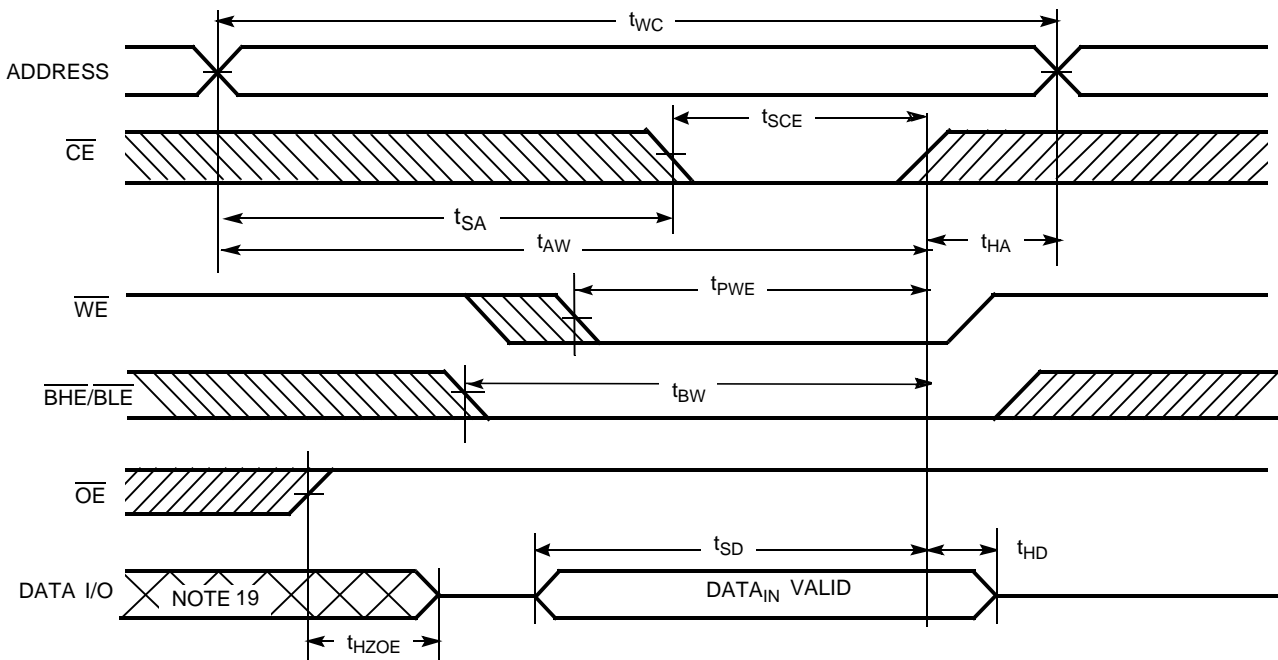
- Full-device AC operation requires linear V_{CC} ramp from V_{DR} to $V_{CC(min.)} > 100 \mu s$ or stable at $V_{CC(min.)} > 100 \mu s$.
- $\overline{BHE.BLE}$ is the AND of both \overline{BHE} and \overline{BLE} . Chip can be deselected by either disabling the chip enable signals or by disabling both \overline{BHE} and \overline{BLE} .
- Test conditions assume signal transition time of 5 ns or less, timing reference levels of $V_{CC(typ.)}/2$, input pulse levels of 0 to $V_{CC(typ.)}$, and output loading of the specified I_{OL}/I_{OH} and 30-pF load capacitance.
- At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE} , t_{HZBE} is less than t_{LZBE} , t_{HZOE} is less than t_{LZOE} , and t_{HZWE} is less than t_{LZWE} for any given device.
- If both byte enables are toggled together this value is 10 ns.
- t_{HZOE} , t_{HZCE} , t_{HZBE} , and t_{HZWE} transitions are measured when the outputs enter a high impedance state.
- The internal write time of the memory is defined by the overlap of \overline{WE} , $\overline{CE} = V_{IL}$, \overline{BHE} and/or $\overline{BLE} = V_{IL}$. All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input set-up and hold timing should be referenced to the edge of the signal that terminates the write.

Switching Characteristics Over the Operating Range^[9] (continued)

Parameter	Description	55 ns		70 ns		Unit
		Min	Max	Min	Max	
t_{HA}	Address Hold from Write End	0		0		ns
t_{SA}	Address Set-up to Write Start	0		0		ns
t_{PWE}	\overline{WE} Pulse Width	40		45		ns
t_{BW}	$\overline{BHE}/\overline{BLE}$ Pulse Width	50		60		ns
t_{SD}	Data Set-up to Write End	25		30		ns
t_{HD}	Data Hold from Write End	0		0		ns
t_{HZWE}	\overline{WE} LOW to High-Z ^[10, 12]		20		25	ns
t_{LZWE}	\overline{WE} HIGH to Low-Z ^[10]	10		10		ns

Switching Waveforms
Read Cycle No. 1 (Address Transition Controlled)^[14, 15]

Read Cycle No. 2 (\overline{OE} Controlled)^[15, 16]

Notes:

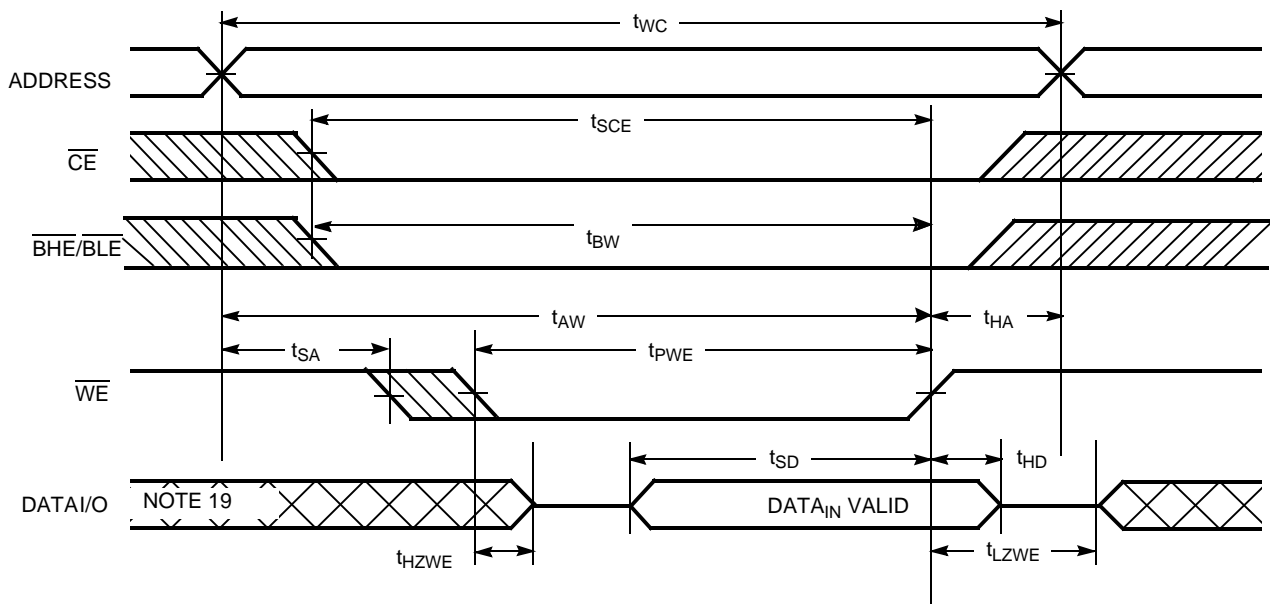
14. Device is continuously selected. \overline{OE} , \overline{CE} = V_{IL} , \overline{BHE} , \overline{BLE} = V_{IL} .
15. \overline{WE} is HIGH for read cycle.
16. Address valid prior to or coincident with \overline{CE} , \overline{BHE} , \overline{BLE} transition LOW.

Switching Waveforms (continued)
Write Cycle No. 1 (\overline{WE} Controlled)^[13, 17, 18]

Write Cycle No. 2 (\overline{CE} Controlled)^[13, 17, 18]

Notes:

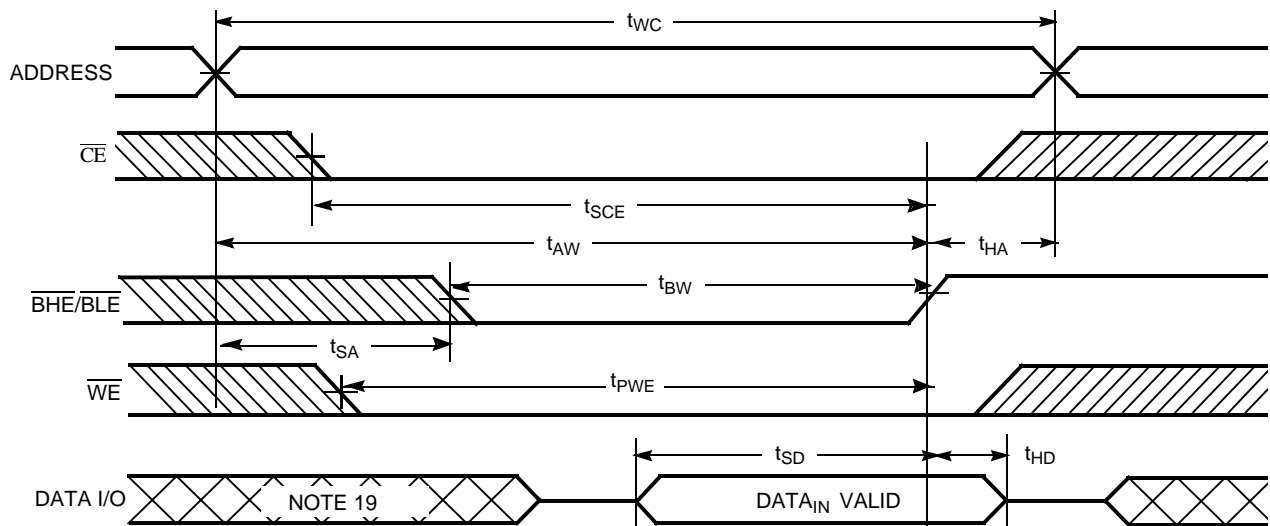
17. Data I/O is high-impedance if $\overline{OE} = V_{IH}$.
18. If \overline{CE} goes HIGH simultaneously with \overline{WE} HIGH, the output remains in a high-impedance state.
19. During this period, the I/Os are in output state and input signals should not be applied.

Switching Waveforms (continued)

Write Cycle No. 3 ($\overline{\text{WE}}$ Controlled, $\overline{\text{OE}}$ LOW)^[18]



Write Cycle No. 4 ($\overline{\text{BHE/BL}}$ Controlled, $\overline{\text{OE}}$ LOW)^[18]





Truth Table

CE	WE	OE	BHE	BLE	Inputs/Outputs	Mode	Power
H	X	X	X	X	High-Z	Deselect/Power-down	Standby (I _{SB})
X	X	X	H	H	High-Z	Deselect/Power-down	Standby (I _{SB})
L	H	L	L	L	Data Out (I/O ₀ -I/O ₁₅)	Read	Active (I _{CC})
L	H	L	H	L	Data Out (I/O ₀ -I/O ₇); I/O ₈ -I/O ₁₅ in High-Z	Read	Active (I _{CC})
L	H	L	L	H	Data Out (I/O ₈ -I/O ₁₅); I/O ₀ -I/O ₇ in High-Z	Read	Active (I _{CC})
L	H	H	L	L	High-Z	Output Disabled	Active (I _{CC})
L	H	H	H	L	High-Z	Output Disabled	Active (I _{CC})
L	H	H	L	H	High-Z	Output Disabled	Active (I _{CC})
L	L	X	L	L	Data In (I/O ₀ -I/O ₁₅)	Write	Active (I _{CC})
L	L	X	H	L	Data In (I/O ₀ -I/O ₇); I/O ₈ -I/O ₁₅ in High-Z	Write	Active (I _{CC})
L	L	X	L	H	Data In (I/O ₈ -I/O ₁₅); I/O ₀ -I/O ₇ in High-Z	Write	Active (I _{CC})

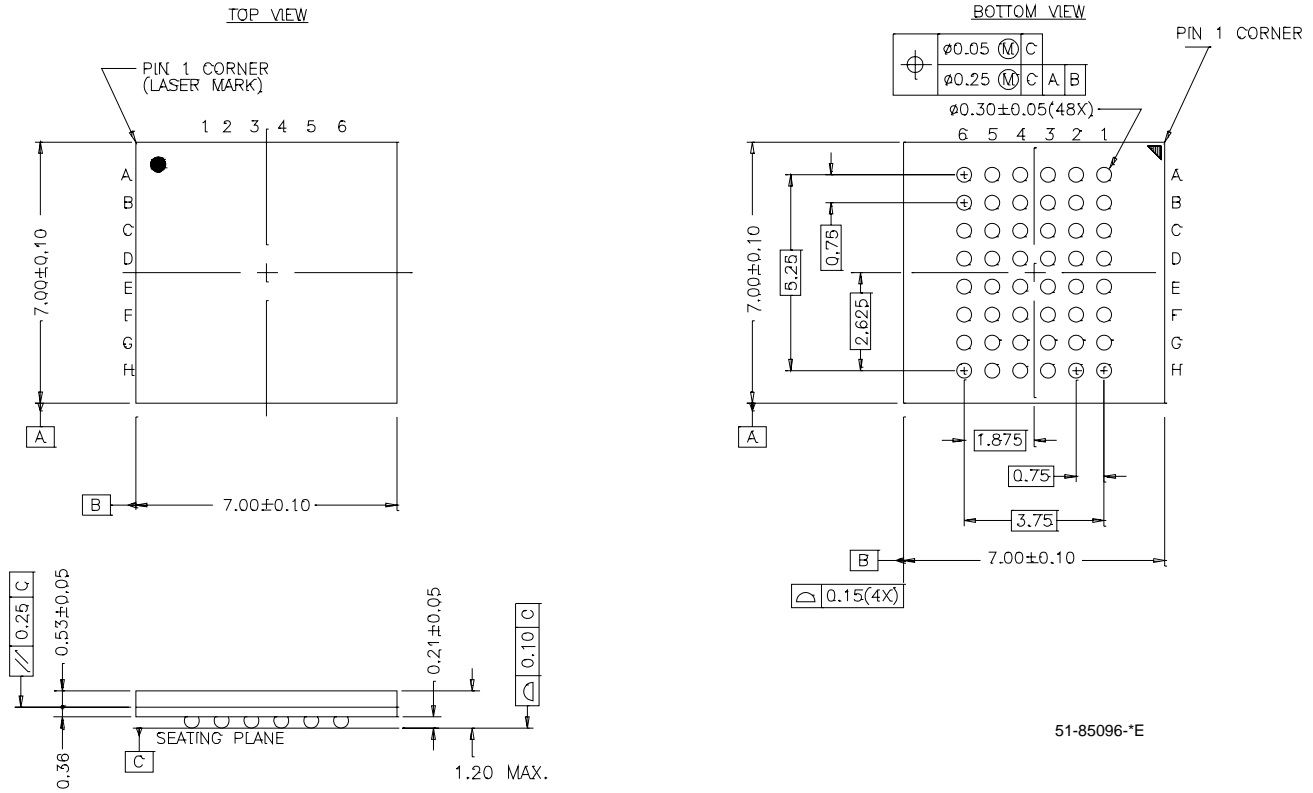
Ordering Information

Speed (ns)	Ordering Code	Voltage Range (V)	Package Name	Package Type	Operating Range
70	CY62137CV25LL-70BAI	2.2-2.7	BA48A	48-ball Fine Pitch BGA (7 mm x 7 mm x 1.2 mm)	Industrial
	CY62137CV25LL-70BVI	2.2-2.7	BV48A	48-ball Fine Pitch BGA (6 mm x 8 mm x 1 mm)	
	CY62137CV30LL-70BAI	2.7-3.3	BA48A	48-ball Fine Pitch BGA (7 mm x 7 mm x 1.2 mm)	
	CY62137CV30LL-70BVI	2.7-3.3	BV48A	48-ball Fine Pitch BGA (6 mm x 8 mm x 1 mm)	
	CY62137CV30LL-70BAXE	2.7-3.3	BA48A	48-ball Fine Pitch BGA (7 mm x 7 mm x 1.2 mm) (Pb-Free)	Automotive
	CY62137CV30LL-70BVXE	2.7-3.3	BV48A	48-ball Fine Pitch BGA (6 mm x 8 mm x 1 mm) (Pb-Free)	
	CY62137CV33LL-70BAI	3.0-3.6	BA48A	48-ball Fine Pitch BGA (7 mm x 7 mm x 1.2 mm)	Industrial
	CY62137CV33LL-70BVI	3.0-3.6	BV48A	48-ball Fine Pitch BGA (6 mm x 8 mm x 1 mm)	
	CY62137CVLL-70BAI	2.7-3.6	BA48A	48-ball Fine Pitch BGA (7 mm x 7 mm x 1.2 mm)	
	CY62137CVLL-70BVI	2.7-3.6	BV48A	48-ball Fine Pitch BGA (6 mm x 8 mm x 1 mm)	
	CY62137CVSL-70BAI	2.7-3.6	BA48A	48-ball Fine Pitch BGA (7 mm x 7 mm x 1.2 mm)	
	CY62137CVSL-70BVI	2.7-3.6	BV48A	48-ball Fine Pitch BGA (6 mm x 8 mm x 1 mm)	
55	CY62137CV25LL-55BAI	2.2-2.7	BA48A	48-ball Fine Pitch BGA (7 mm x 7 mm x 1.2 mm)	
	CY62137CV25LL-55BVI	2.2-2.7	BV48A	48-ball Fine Pitch BGA (6 mm x 8 mm x 1 mm)	
	CY62137CV30LL-55BAI	2.7-3.3	BA48A	48-ball Fine Pitch BGA (7 mm x 7 mm x 1.2 mm)	
	CY62137CV30LL-55BVI	2.7-3.3	BV48A	48-ball Fine Pitch BGA (6 mm x 8 mm x 1 mm)	
	CY62137CV33LL-55BAI	3.0-3.6	BA48A	48-ball Fine Pitch BGA (7 mm x 7 mm x 1.2 mm)	
	CY62137CV33LL-55BVI	3.0-3.6	BV48A	48-ball Fine Pitch BGA (6 mm x 8 mm x 1 mm)	

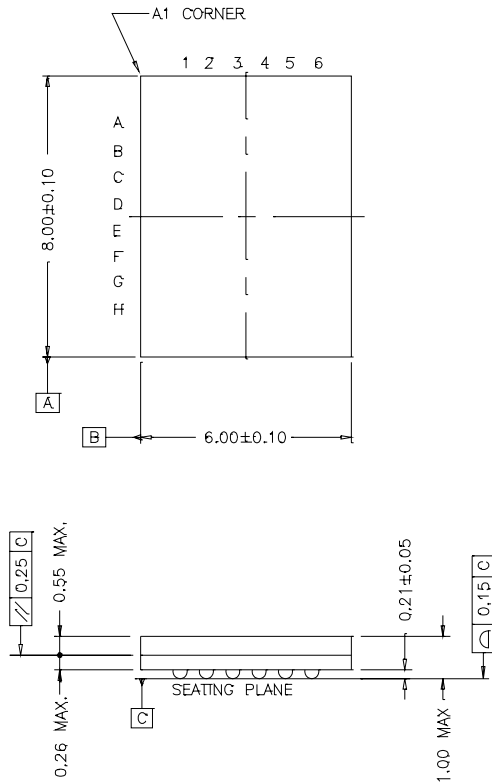
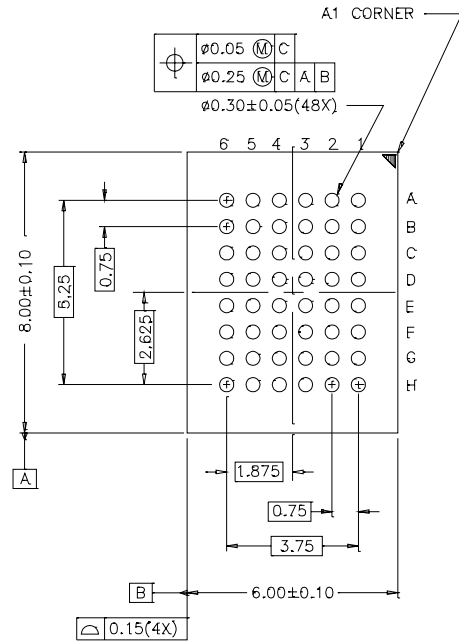
Shaded areas contain advance information. Please contact your local sales representative for availability of these parts.

Package Diagrams

48-ball (7.00 mm x 7.00 mm x 1.2 mm) FBGA BA48A



51-85096*E

Package Diagrams (continued)
48-Lead VFBGA (6 x 8 x 1 mm) BV48A
TOP VIEW

BOTTOM VIEW


51-85150-B

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Document History Page

Document Title: CY62137CV25/30/33 MoBL[®] and CY62137CV MoBL[®] 2M (128K x 16) Static RAM				
Document Number: 38-05201				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	112393	02/19/02	GAV	New Data Sheet (advance information)
*A	114015	04/25/02	JUI	Added BV package diagram Changed from Advance Information to Preliminary
*B	117064	07/12/02	MGN	Changed from Preliminary to Final
*C	118122	09/10/02	MGN	Added new part number: CY62137CV with wider voltage (2.7V – 3.6V). Added new SL power bin for new part number. For T _{AA} = 55 ns, improved t _{PWE} min. from 45 ns to 40 ns. For T _{AA} = 70 ns, improved t _{PWE} min. from 50 ns to 45 ns. For T _{AA} = 70 ns, improved t _{LZWE} min. from 5 ns to 10 ns.
*D	118761	09/23/02	MGN	Improved Typ. I _{CC} spec to 7 mA (for 55 ns) and 5.5 mA (for 70 ns). Improved Max I _{CC} spec to 15 mA (for 55 ns) and 12 mA (for 70 ns). For T _{AA} = 55 ns, improved t _{LZWE} min. from 5 ns to 10 ns. Changed upper spec. for Supply Voltage to Ground Potential to V _{CCMAX} + 0.5V. Changed upper spec. for DC Voltage Applied to Outputs in High-Z State and DC Input Voltage to V _{CC} + 0.3V.
*E	343877	See ECN	PCI	Added Automotive Information in Operating Range, DC and Ordering Information Table